

C1812X563JATACTU

Aliases (C1812X563JATAC7800)

SMD Comm X8G HT150C Flex, Ceramic, 0.056 uF, 5%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information			
Series	SMD Comm X8G HT150C Flex		
Style	SMD Chip		
Description	SMD, MLCC, High Temperature, Ultra-Stable		
Features	High Temperature, Ultra-Stable		
RoHS	Yes		
Termination	Flexible Termination		
Marking	No		
AEC-Q200	No		
Typical Component Weight	67 mg		
Shelf Life	78 Weeks		
MSL	1		

Dimensions	
Chip Size	1812
L	4.5mm +/-0.4mm
W	3.2mm +/-0.3mm
Т	1.25mm +/-0.15mm
S	2.3mm MIN
В	0.7mm +/-0.35mm

W	3.2mm +/-0.3mm
Т	1.25mm +/-0.15mm
S	2.3mm MIN
В	0.7mm +/-0.35mm
Packaging Specifications	

1000

Packaging

Packaging Quantity

Specifications			
Capacitance	0.056 uF		
Measurement Condition	1 kHz 1.0Vrms		
Tolerance	5%		
Voltage DC	250 VDC		
Dielectric Withstanding Voltage	625 VDC		
Temperature Range	-55/+150°C		
Temp. Coefficient	X8G		
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms		
Dissipation Factor	0.1% 1 kHz 1.0Vrms		
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours		
Insulation Resistance	17.8571 GOhms		

Ag	Aging Rate	Time is 1000
Ins	nsulation Resistance	17.8571 GOhm

T&R, 180mm, Plastic Tape

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